EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	50	("6977211" "6326698" "6337122" "6432752" "6461881" "6468891" "6482576" "6489007" "6500746" "6506671" "6514798" "6524346" "6525408" "6529027" "6531335" "6537482" "6537842" "6544465" "6544821" "6548897" "6549821" "6562278" "6562661" "6569753" "6585927" "6593171" "6607689" "6611053" "6630365" "6630730" "6632732" "6634100" "6635333" "6649444" "6703105" "6706374" "6709795" "6730998" "6740476" "6740962" "6746899" "6762502" "6764933" "6764935" "6767815" "6770514" "6773957" "6780744" "6791164" "6794224").pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 10:09
L2	0	l1 not micron.as.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 10:09
L3	2	"5384008".pn. or "5304248".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 10:21
L4	220	shadow adj ring and deposition	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 10:21
L5	97	l4 and (backside)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 10:24
L6	2	l5 and programmable	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 10:22
L7	74	l4 and (backside) same deposition	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 10:25
L8	69	l7 and vacuum	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 10:25
L9	22	l7 and vacuum same pedestal	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 10:27
L10	0	l4 and 700/119-120.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 10:27
L11	328	700/119-120.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 10:27
L12	5	l11 and backside	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 10:28
L13	18	l11 and (back$5 with (wafer or substrate))	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 10:31
L14	9	l11 and vacuum with support	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 10:31
L15	29	(US-20030173713-$ or US-20030114016-$ or US-20010032111-$ or US-20030070915-$ or US-20050133527-$).did. or (US-6337122-$ or US-6021358-$ or US-5506607-$ or US-6158346-$ or US-5287435-$ or US-5740051-$ or US-5278442-$ or US-6153034-$ or US-6463349-$ or US-6830643-$ or US-6660209-$ or US-5376180-$ or US-5484314-$ or US-5545367-$ or US-5925411-$ or US-4575330-$ or US-6066575-$ or US-6550484-$ or US-5304248-$ or US-5384008-$ or US-6051286-$ or US-6231674-$ or US-6697694-$ or US-5260009-$).did.	US-PGPUB; USPAT	OR	OFF	2006/02/17 10:34

EAST Search History

L16	1	l15 and pressure same eject$3	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 10:38
L17	12	l15 and pressure same remov$5	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 12:09
L18	13	l11 and pressure with substrate	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 12:11
L19	26	"700"/$.ccls. and remov$4 with pressure with substrate	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/17 12:11
S1	1	"6337122".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/25 09:18
S2	1	"5740051".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:24
S3	1	stereolithography and retention adj lip	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 12:27
S4	303	retention adj lip	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 12:27
S5	4	S4 and semiconductor	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:07
S6	7	S4 and wafer	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:10
S7	0	700/121.ccls. and (consolidation or unconsolidated) and (wafer or semiconductor) and seal same support	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:10
S8	73	(consolidation or unconsolidated) and (wafer or semiconductor) and seal same support	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:11
S9	97	(consolidation or unconsolidated) and (substrate or wafer or semiconductor) and seal same support	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:11
S10	71	S9 and lip	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:11
S11	71	S10 and bottom	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:12
S12	9	S11 and (stereolithography or lithograph$3)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:25
S13	19	("4375025" | "4585931" | "4638144" | "4707722" | "4753863" | "4861620" | "4945204" | "5278442" | "5329090" | "5357077" | "5985510" | "6153034").PN. OR ("6337122").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/24 13:21
S14	1	"5506607".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:24
S15	214	stereolithography and (consolidation or unconsolidated)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:33

EAST Search History

S16	31	S15 and retention	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:26
S17	7	("6337122").URPN.	USPAT	OR	OFF	2005/01/24 13:29
S18	12	("4375025" | "4585931" | "4638144" | "4707722" | "4753863" | "4861620" | "4945204" | "5278442" | "5329090" | "5357077" | "5985510" | "6153034").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/24 13:31
S19	0	S18 and (wafer or substrate) same bottom	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/24 13:31
S20	4	S18 and (wafer or substrate)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/24 13:32
S21	0	S20 and retention	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/24 13:32
S22	0	S20 and retain	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/24 13:32
S23	1	S20 and support	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/24 13:32
S24	368	stereolithography and (wafer or substrate) same support	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:33
S25	83	S24 and (retain or retention or retained)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:38
S26	26	700/120.ccls. and (retain or retention or retained)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:44
S27	23	700/120.ccls. and (wafer or substrate) and support	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 14:11
S28	1	"6073056".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:48
S29	1	"6482576".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:49
S30	1	"6549821".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 13:49
S31	146	700/120.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 14:11
S32	2	S31 and wafer near5 support	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 15:14
S33	0	S31 and wafer near5 bottom	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 14:12
S34	10	stereolithography and wafer near5 bottom	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 14:14
S35	75	stereolithography and wafer and vacuum and support	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 14:16

EAST Search History

S36	8	S35 and wafer near5 (backside or bottom or underneath)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 14:17
S37	209	stereolithography and substrate and vacuum and support	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 14:16
S38	32	S37 and substrate near5 (backside or bottom or underneath)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 14:18
S39	19	S37 and receptacle	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 17:08
S40	22	S38 not S39	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 14:19
S41	85	"438"/$.ccls. and stereolithography	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 14:19
S42	1	wafer adj carrier and stereolithography	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 14:33
S43	1785	spacer same support same substrate	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 14:37
S44	163	substrate same unconsolidated	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 15:15
S45	0	S44 and wafer adj carrier	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 16:28
S46	15	wafer adj carrier and consolidation	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 16:28
S47	24231	meniscus	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 17:08
S48	121	meniscus adj blade	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 17:12
S49	119	S48 and stereolithography	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 17:12
S50	114	S49 and (wafer or substrate) same support	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 17:09
S51	74	S50 not micron.as.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 17:09
S52	114	S50 not britt.as.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 17:09
S53	114	S50 not brit.as.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 17:09
S54	2	S48 not S49	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 17:10

EAST Search History

S55	11004	air adj knife	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 17:12
S56	11	S55 and stereolithography	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/24 17:12
S57	86	kosowski.xa.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/25 09:19
S58	10	retention adj lip and (wafer or substrate) and support	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/25 10:11
S59	12	retention adj lip and (wafer or substrate)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/25 10:12
S60	2	S59 not S58	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/25 10:11
S61	2	retention adj lip same (wafer or substrate)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/25 12:43
S63	178	stereolithography and consolidation	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/25 12:50
S64	152	S63 and (wafer or substrate)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/25 12:50
S65	101	S64 not micron.as.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/25 12:51
S66	100	S65 and computer	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/25 12:51
S67	3	S66 and 700/120-121.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/25 12:51
S68	7	S66 and "700"/$.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/25 12:51
S69	5	"3889355".pn. or "4027246".pn. or "4728252".pn. or "5789890".pn. or "6336204".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 14:52
S70	101	kosowski.xa.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 14:51
S71	1	"6337122".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 14:54
S72	0	S69 and underneath	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 14:54
S73	2	S69 and bottom	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 16:09
S74	101	700/120.ccls. and support	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 16:09

EAST Search History

S75	25	S74 and (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 16:20
S76	0	S69 and stereolithography	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 16:20
S77	0	S69 and consolidated	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 16:31
S78	0	stereolithography and miniscus	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 16:31
S79	206	stereolithography and meniscus	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:19
S80	202	S79 and support	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 16:31
S81	145	S80 not micron.as.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 16:46
S82	82	S81 and consolidation	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 16:51
S83	7	S82 and "700"/$.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 17:04
S84	10	S74 and consolidat$3	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 17:04
S85	10	S74 and consolidat$4	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/27 17:04
S86	40	700/120.ccls. and mark$3	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 13:21
S87	18	S86 and (wafer or substrate)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 13:21
S88	17	("4577056" | "4696525" | "5028983" | "5173220" | "5264061" | "5278442" | "5433260" | "5484314" | "5641996" | "5675122" | "5705117" | "5754408" | "5801073" | "5834840" | "5953594" | "6048744" | "6299057").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 13:29
S89	6	vacuum and sealing same retention and (wafer or substrate) and "700"/$.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 14:33
S90	262	vacuum and sealing same retention and (wafer or substrate)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 13:39
S91	11	S90 and stereolithography	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 13:37
S92	5	S91 not S89	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 13:37
S93	11	sealing same retention same (wafer or substrate) and stereolithography	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 13:39

S94	848	438/758.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 14:00
S95	1	S94 and stereolithography	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 14:00
S96	54	("4996010" | "4999143" | "5015424" | "5058988" | "5059021" | "5059359" | "5071337" | "5096530" | "5104592" | "5123734" | "5130064" | "5133987" | "5141680" | "5143663" | "5164128" | "5173220" | "5174931" | "5182055" | "5182056" | "5182715" | "5184307" | "5192469" | "5192559" | "5209878" | "5234636" | "5238639" | "5248456" | "5256340" | "5264061" | "5267013" | "5278442" | "5321622" | "5345391" | "5358673" | "5447822" | "5484314" | "5495328" | "5501824" | "5545367" | "5641391" | "5693144" | "5695707" | "5705117" | "5776409" | "5779967" | "5840239" | "5855718" | "5855836" | "5897825" | "5902537" | "5902538" | "5904889" | "5943235" | "5945058").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 13:50
S97	12	S96 and (substrate or wafer)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 14:01
S98	0	S97 and retention	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 14:20
S99	1	S96 and retention	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 14:00
S100	1250	438/758-760.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 14:00
S101	1	S100 and stereolithography	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 14:19
S102	37	S100 and retention	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 14:00
S103	37	S102 and (substrate or wafer)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 14:19
S104	1	S100 and consolidation	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 14:19
S105	903	S100 and deposition	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 14:19
S106	894	S105 and (substrate or wafer)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 14:19
S107	30	S106 and retention	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 14:20
S108	9	S107 and seal$4	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 14:20

S10 9	51	("3809050" | "4184188" | "4261762" | "4403567" | "4457359" | "4466872" | "4508161" | "4512391" | "4523985" | "4527620" | "4530635" | "4535834" | "4567938" | "4575408" | "4603466" | "4682566" | "4687682" | "4709655" | "4724621" | "4738748" | "4743570" | "4767641" | "4804560" | "4817558" | "4857142" | "4859304" | "4911103" | "4960488" | "4986215" | "4990374" | "5000113" | "5033407" | "5033538" | "5037262" | "5094885" | "5133284" | "5138973" | "5198753" | "5228501" | "5230741" | "5238499" | "5292554" | "5304248" | "5326725" | "5328722" | "5374594" | "5376180" | "5534072" | "5574247" | "5578532" | "5620525").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 14:26
S11 0	1259	118/308.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 14:32
S11 1	5	S110 and backside	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 14:32
S11 2	12	vacuum and sealing same retention and (wafer or substrate) and backside	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 14:36
S11 3	90	seal$4 same (wafer or substrate) same backside and powder	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 14:53
S11 4	0	stereolithography and substrated same protection	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 14:54
S11 5	59	stereolithography and substrate same protection	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 14:54
S11 6	206	stereolithography and meniscus	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:19
S11 7	167	S116 and (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:20
S11 8	103	S117 not micron	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:22
S11 9	56	S118 and seal$4	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:20
S12 0	0	S118 and gasket	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:20
S12 1	82	S117 not trask	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:22
S12 2	25	S117 not (trask or traskbritt)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:27
S12 3	62	material adj consolidation and substrate	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:26
S12 4	42	S123 not (trask or traskbritt)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:33
S12 5	13	("3264385" | "3390447" | "4113480" | "4575330" | "4698907" | "4752352" | "4863538" | "5059266" | "5088047" | "5094935" | "5156697").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 15:29

S126	0	S125 and substate	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 15:30
S127	4	S125 and substrate	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 15:32
S128	21	stereolithography and platform and secure with substrate	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 15:32
S129	67	deposition and powder and platform and secure with substrate	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 15:33
S130	49	S129 not (trask or traskbritt)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:13
S131	247	438/760.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:19
S132	233	S131 and substrate	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:19
S133	25	S131 and seal$3	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:49
S134	5	("6550484").URPN.	USPAT	OR	OFF	2005/07/28 15:53
S135	2	("5925411" | "6461155").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/28 15:55
S136	198	438/759.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:19
S137	25	S136 and substrate and seal$3	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:19
S138	15	(US-20010032111-$ or US-20030114016-$).did. or (US-5740051-$ or US-6153034-$ or US-6337122-$ or US-6463349-$ or US-6830643-$ or US-5484314-$ or US-5278442-$ or US-5545367-$ or US-5376180-$ or US-5925411-$ or US-6660209-$ or US-6550484-$ or US-6066575-$).did.	US-PGPUB; USPAT	OR	OFF	2005/07/28 16:37
S139	2	S138 and consolidat$3	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:38
S140	11	S138 and deposition	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:38
S141	6	S140 and powder	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:39
S142	5	S141 and (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:44
S143	9	S140 and (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:45
S144	4	S143 not S142	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:46

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S14 5	950	laser adj sintering	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:46
S14 6	30	S145 and (substrate or wafer) and backside	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:52
S14 7	1	"4323756".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:52
S14 8	8596	(dmd or sls)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:52
S14 9	268	S148 and (substrate or wafer) and backside	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:52
S15 0	224	S149 and support	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:52
S15 1	30	S149 and support near5 wafer	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:54
S15 2	24	stereolithography and support near5 wafer	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:57
S15 3	18	stereolithography and secur$3 near5 wafer	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:57
S15 4	14	S153 not S152	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 16:57
S15 5	153	wafer same stereolithography	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:12
S15 6	140	S155 and (support or pedestal)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:12
S15 7	12	S156 and lip	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:13
S15 8	41	S155 not (trask or traskbritt)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:15
S15 9	19	S158 not micron	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:15
S16 0	1455	(metal adj deposition or laser adj sintering) same wafer	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:15
S16 1	61	S160 and lip	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:15
S16 2	61	S161 not (trask or traskbritt)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 12:05
S16 3	0	wafer adj pedestal and stereolithography	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:59

S16 4	0	wafer near3 pedestal and stereolithography	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:25
S16 5	3	S162 not (gas or plasma)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:25
S16 6	17	wafer and lip and stereolithography	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:28
S16 7	11	wafer and lip and material adj consolidation	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:28
S16 8	18	programmed adj material adj consolidation	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:28
S16 9	51	wafer adj pedestal and powder	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 12:01
S17 0	9	S169 and lip	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:59
S17 1	26	wafer with pedestal and powder and laser	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 12:04
S17 2	153	wafer same stereolithography	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 12:05
S17 3	19	S172 not (trask or traskbritt or micron)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 12:05
S17 4	284	substrate same stereolithography	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 12:05
S17 5	81	S174 not (trask or traskbritt or micron)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 13:41
S17 6	0	S175 and backside	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 12:05
S17 7	1	S175 and lip	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 12:05
S17 8	1	"4575330".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 12:32
S17 9	5	S175 and retention	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 12:32
S18 0	19	(US-20010032111-$ or US-20030114016-$ or US-20030070915-$ or US-20050133527-$ or US-20030173713-$).did. or (US-5278442-$ or US-5376180-$ or US-5484314-$ or US-5545367-$ or US-5740051-$ or US-5925411-$ or US-6066575-$ or US-6153034-$ or US-6337122-$ or US-6463349-$ or US-6550484-$ or US-6660209-$ or US-6830643-$ or US-4575330-$).did.	US-PGPUB; USPAT	OR	OFF	2005/07/29 14:08
S18 1	4	S180 and (retain or retention)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 13:37

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S18 2	1	"20030173713"	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 13:41
S18 3	1806	substrate with receptacle	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 13:41
S18 4	46	S183 and stereolithography	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 13:41
S18 5	3	S184 not (trask or traskbritt or micron)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 14:04
S18 6	1	"5230741".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 14:04
S18 7	19	(US-20010032111-$ or US-20030114016-$ or US-20030070915-$ or US-20050133527-$ or US-20030173713-$).did. or (US-5278442-$ or US-5376180-$ or US-5484314-$ or US-5545367-$ or US-5740051-$ or US-5925411-$ or US-6066575-$ or US-6153034-$ or US-6337122-$ or US-6463349-$ or US-6550484-$ or US-6660209-$ or US-6830643-$ or US-4575330-$).did.	US-PGPUB; USPAT	OR	OFF	2005/07/29 14:08
S18 8	4	S187 and backside	US-PGPUB; USPAT	OR	OFF	2005/07/29 14:18
S18 9	9	S187 and seal$3	US-PGPUB; USPAT	OR	OFF	2005/07/29 15:38
S19 0	3	S187 and lamina	US-PGPUB; USPAT	OR	OFF	2005/07/29 15:40
S19 1	3	S187 and wiper	US-PGPUB; USPAT	OR	OFF	2005/07/29 15:48
S19 2	1	"4929402".pn.	US-PGPUB; USPAT	OR	OFF	2005/07/29 15:59
S19 3	7	S187 and spray$3	US-PGPUB; USPAT	OR	OFF	2005/07/29 16:05
S19 4	1	"6158346".pn.	US-PGPUB; USPAT	OR	OFF	2005/07/29 16:05
S19 5	1	S194 and remov$5	US-PGPUB; USPAT	OR	OFF	2005/07/29 16:27
S19 6	1	"6158346".pn.	US-PGPUB; USPAT	OR	OFF	2005/07/29 16:27
S19 7	1	"6337122".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/16 16:54
S19 8	1	"6337122".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/16 17:33
S20 0	1	"5506607".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/16 17:49
S20 1	7	US-5287435-$.DID. OR US-5482659-$.DID. OR US-5508489-$. DID. OR US-6021358-$.DID. OR US-6158346-$.DID. OR US-6337122-$.DID. OR US-6483596-$.DID.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/16 17:52
S20 2	3	"20020090410" or "20030173713" or "20040251242"	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2006/02/16 17:52